



Tracewell T-FX2

BASED ON: The Dell EMC PowerEdge FX architecture. Converged platform houses flexible blocks of server, storage and I/O resources while providing efficiency through shared power, networking and management.

USE CASE: Ideal for customers that require an enterprise-class, converged compute platform for space-constrained, forward deployed or tactical environments.



5.2"H x 19.0"W x 23.7"D
(17.5"W not including ears)

FORM FACTOR HIGHLIGHTS:

Enterprise class, converged platform in a short-depth form factor – only 23.7" from front to back.

Benefits

DELL TECHNOLOGIES

Enterprise-class modular infrastructure that combines the density and efficiency of blades with the simplicity and cost benefits of rack systems. Flexible and customizable servers, storage and networking.

TRACEWELL PLATFORMS

Features Dell EMC FX architecture in a short-depth form factor. Offers less weight, consumes less power and increases cooling capacity compared to a standard Dell EMC product and can be customized to meet specific program requirements or integrated with critical third-party technologies.

DELL TECHNOLOGIES + TRACEWELL

Electrically identical to standard Dell EMC products. "Plug and play" components between Dell EMC products and Tracewell platforms. Order through Dell EMC (Dell EMC part number) and eligible for Dell EMC warranty, service, support and secure supply chain.

The Tracewell T-FX2 Specifications Summary

The Tracewell T-FX2 accepts standard Dell hardware configurations.

STANDARD DELL EMC PRODUCT CONFIGURATIONS

PROCESSOR TYPE	<p>Quarter-Width (QW): Intel® Xeon® E5-2600 v4 & v5 family of processors, up to 16 cores per processor (1 or 2 processors).</p> <p>Half-Width (HW): Intel® 2nd generation Xeon® Scalable processors, up to 28 cores per processor (1 or 2 processors).</p> <p>Full-Width (FW): Intel Xeon E5-4600 v3 & v4, up to 22 cores (4 processors).</p>
MEMORY ARCHITECTURE	<p>QW: 8 DDR4 slots, supports 2133MT/s LRDIMM and RDIMM, 512GB Max DDR4.</p> <p>HW: 16 DDR4 DIMM slots, supports RDIMM / LRDIMM, up to 2933MT/s speeds, 2TB Max DDR4.</p> <p>FW: 48 DDR4 Slots, supports 2133 & 2400MT/s LRDIMM and RDIMM, 3TB Max DDR4.</p> <p>Number of Sockets: QW: 8, HW: 16, FW: 48.</p> <p>Maximum RAM: QW: 512GB, HW: 2048GB, FW: 3072GB.</p>
RAID CONTROLLER	Hardware RAID, Levels 0, 1, 5, 10 or pass through.
STORAGE	<p>Processing Sleds: QW: Up to two 1.8", HW: Up to two 2.5" or (8) 1.8" drives. FW: Up to (16) 1.8".</p> <p>Hot-swappable, SAS/SATA/PCIe, SSD/HDD.</p> <p>Internal SD vFlash site. Optional internal USB and dual SD sites (hypervisor).</p>
VIDEO	Internal SD vFlash site. Optional internal USB and dual SD sites (hypervisor).
SLED SLOTS	Sled bay scalable to include up to eight (QW), four (HW), or two (FW) processing sleds. Accepts standard FC430 and FC640 processing sleds with appropriate configuration or filler panels.
I/O MODULES	Ethernet: Supports up to 2 I/O aggregator modules. Modules are available in pass-through and switching configurations.
CHASSIS MANAGEMENT CONTROLLER	Single, dual-port chassis management module. Two dedicated 10/100/1000Mb RJ45 ports, one for external management network and one for daisy chaining or NIC failover. Serial 9-pin, DTE, 16550 compatible.
FRONT ACCESSIBLE I/O	<p>One USB 2.0 connector for keyboard and mouse support.</p> <p>One additional USB 2.0 connector.</p> <p>One 15-pin VGA video connector. KVM selector switch. On / Standby switch.</p>

POWER SUPPLY

Up to two power supplies supported. Available in 2400W / 2000W / 1600W output (per PS). N+1 capable.

High-line operation up to 2400W with N+1 redundancy or 3000W* non-redundant.

Low-line operation up to 1400W with N+1 redundancy or 2800W non-redundant.

Input voltage: 90-264 VAC.

Maximum inrush current: 25A (35A, 2400W).

*CMC system limits power usage within the system architecture.

COOLING

Two rear removable fan modules with high-pressure fans. Independent cooling provided to PCIe slots.

ENVIRONMENTAL

Normal Operating Temp: 10°C to 35°C (50°F to 95°F).

Expanded Operating Temp: -5°C to 45°C (23°F to 113°F) with some restrictions.

Storage Temp: -40°C to 65°C (-40°F to 149°F).

EMC: Enterprise class FCC emissions.

Optional EMI shielding and D38999 connectors for MIL-STD-461 (adds 1U).

TRACEWELL SYSTEMS PRODUCT CONFIGURATIONS

CHASSIS

Bonded aluminum low-mass chassis for rigidity with minimum weight.

RACK INSTALLATION & OPTIONS

19" rack mount per EIA specification. Front and rear mounting points to allow hard mounting into racks; rear pin option to allow blind mating into racks. Additional mounting locations for sled lock bars. Front handles. Optional: Rack mount slides, removable front guard with particle filter and line cord retainer kit.

For more information, see the Tracewell T-FX2 Data Sheet.

ABOUT TRACEWELL SYSTEMS

For more than 40 years Tracewell has enabled the nation's largest military and commercial organizations to deliver powerful and reliable computing solutions in environments where size, weight, power and other constraints present challenges that cannot be met by standard computing systems. Tracewell Systems have been recognized by the top names in the defense and technology sectors for their commitment to Trusted Innovation – a process where the company solves previously impossible, sensitive, mission-critical platform challenges through customer solution design, engineering and manufacturing, all under one roof.

More information: www.tracewell.com.

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April 2021 | Version 1.0 Tracewell T-FX2 At A Glance
